

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS-Nummer: 330866844

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Deklarationen genehmigt durch

Udo Steinebrunner, Product Manager, -

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Materialien und Stoffe

Verwendung/Andordnung	Material group	% w/w des Materials im Artikel	Substances in the material	CAS Number	% w/w des Stoffs im Artikel
Chip (die)	Other inorganic materials	2.00000%	Nickel REACH-Artikel 67 Ausnahme	8049-31-8	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethylsiloxane rubber	63394-02-5	25.00000%
			Silicon	7440-21-3	62.50000%
Die attach	Lead and Lead alloys	1.20000%	SILVER METAL	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead EU RoHS-Ausnahme 7(a) Exempt from other regulatory requirements	7439-92-1	92.50000%
Encapsulation	Other thermoplastics	40.00000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE Exempt from industry substance restrictions	1309-64-4	0.80000%
			3,5,3,5-Tetrabromobisphenol A (TBBA)	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz silica	14808-60-7	70.30000%
Leadfinish	Tin plating	0.50000%	Tin	7440-31-5	100.00000%
Leadframe	Copper alloys	56.30000%	Copper	7440-50-8	100.00000%

Beigefügte Artikelliste

Artikelnummer	Artikelbezeichnung
GBUxxX	Bridge Rectifier Single Inline

Based on the information currently available, these substances do not pose any risk if the articles are used as intended (including disposal). Additional information is not necessary to allow safe use of the article.